

IMEC306.001AUS

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Szlufcik *et al.*
Appl. No. : 10/609,015
Filed : June 27, 2003
For : SEMICONDUCTOR ETCHING
PASTE AND THE USE THEREOF
FOR LOCALIZED ETCHING OF
SEMICONDUCTOR
SUBSTRATES
Examiner : Vinh, L.
Group Art Unit : 1765

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

October 30, 2006

(Date)

Rose M. Thiessen, Reg. No. 40,202

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed May 2, 2006, Applicants respectfully request that the Examiner enter the following amendments and consider the following remarks.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.

11/06/2006 RHEBRAHT 00000055 10609015

01 FC:1253
02 FC:1202

1020.00 OP
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